

3A Avg.

120 Volts

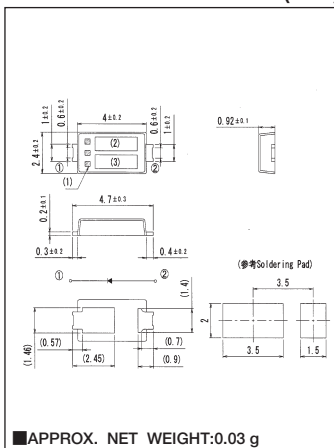
SBD

NA03HSA12

■最大定格 Maximum Ratings

Item	Symbol	Conditions	Unit	
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	$V_{RRM}$	120	V	
平均整流電流 Average Rectified Forward Current	$I_O$	50Hz、正弦半波通電抵抗負荷 50Hz Half Sine Wave Resistive Load	$T_a=30^{\circ}C^*$ $V_{RM}=60V$ $T_l=115^{\circ}C$ $V_{RM}=60V$ T <sub>lead</sub> Temperature	1.2 A
				3.0 A
実効順電流 R.M.S. Forward Current	$I_F(RMS)$	4.71	A	
サージ順電流 Surge Forward Current	$I_{FSM}$	60	A	
動作接合温度範囲 Operating Junction Temperature Range	$T_{jw}$	-40~+150	°C	
保存温度範囲 Storage Temperature Range	$T_{stg}$	-40~+150	°C	

■OUTLINE DRAWING(mm)

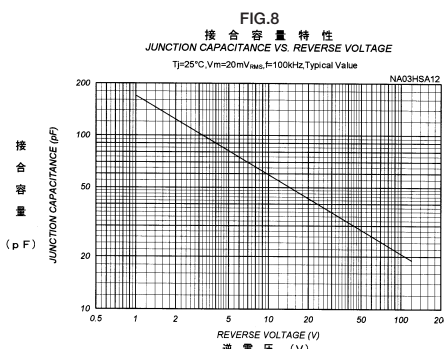
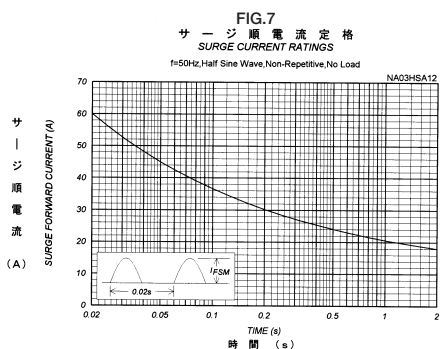
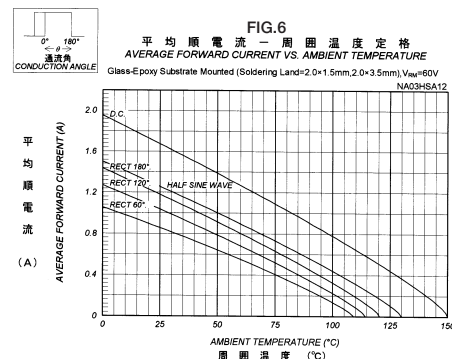
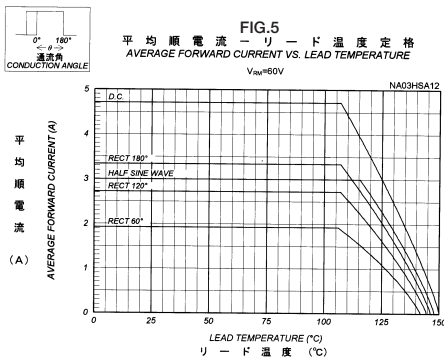
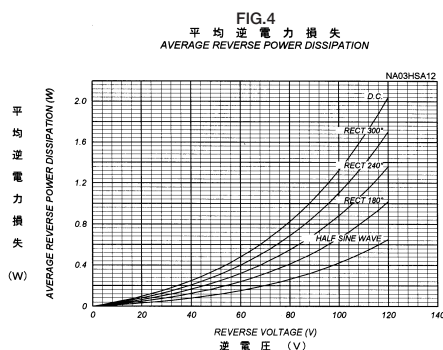
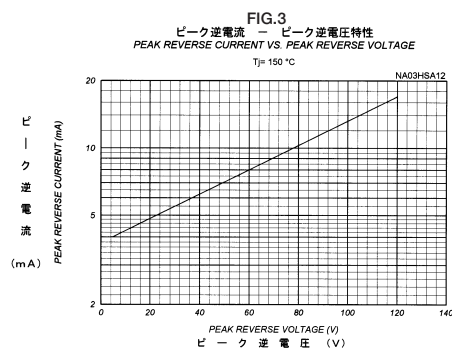
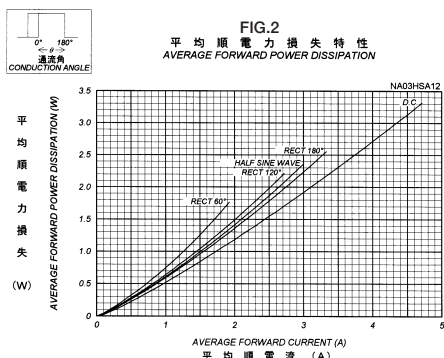
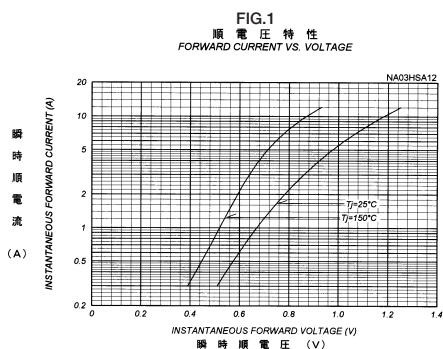


■電氣的・熱的特性 Electrical/Thermal Characteristics

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
ピーク逆電流 Peak Reverse Current	$I_{RM}$	$T_j=25^{\circ}C, V_{RM}=120V$	—	—	70	$\mu A$
ピーク順電圧 Peak Forward Voltage	$V_{FM}$	$T_j=25^{\circ}C, I_{FM}=3A$	—	—	0.86	V
熱抵抗 Thermal Resistance	$R_{th(j-a)}$	接合部・周囲間 Junction to Ambient	—	—	130	°C/W
	$R_{th(j-l)}$	接合部・リード間 Junction to Lead	—	—	13	°C/W

\*プリント基板実装/Glass-Epoxy Substrate mounted (Soldering Lands= 2.0 × 1.5 mm, 2.0 × 3.5 mm)

■定格・特性曲線



接合容量特性